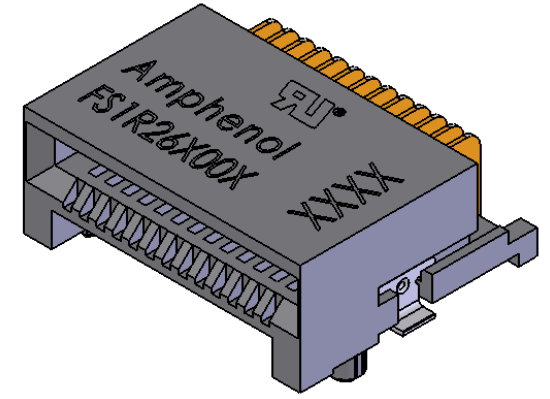
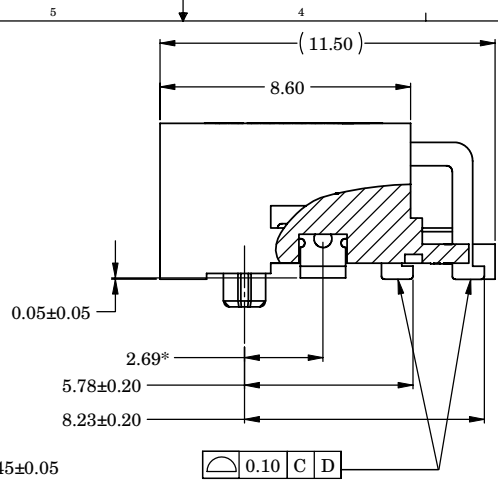
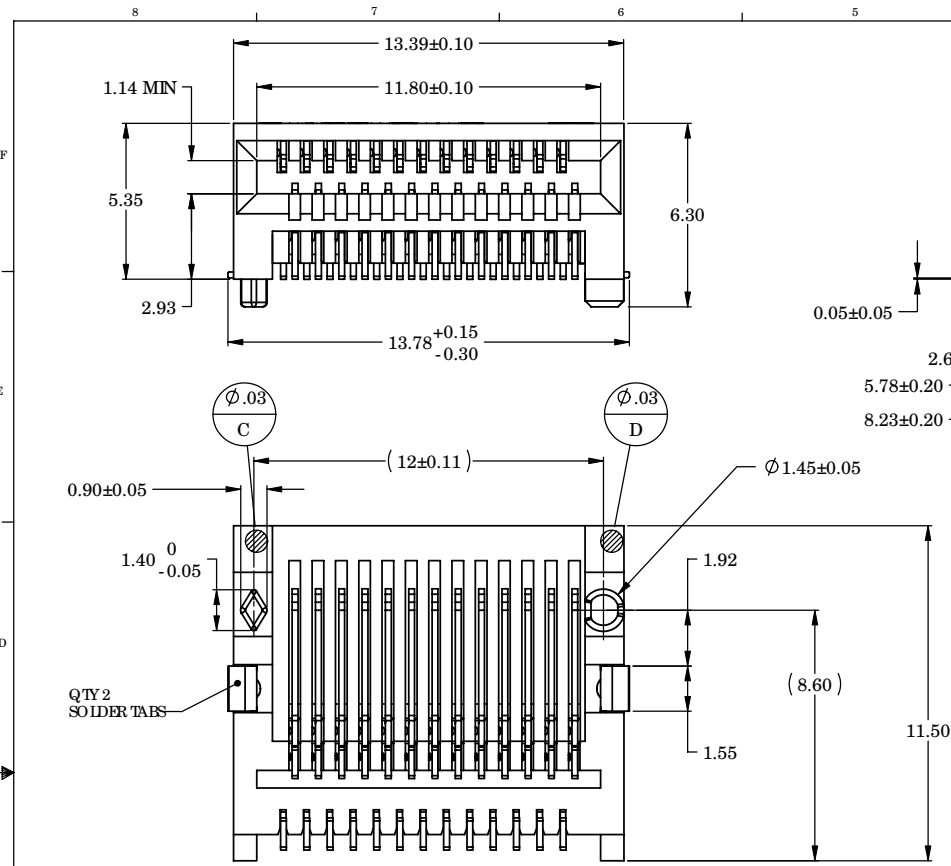
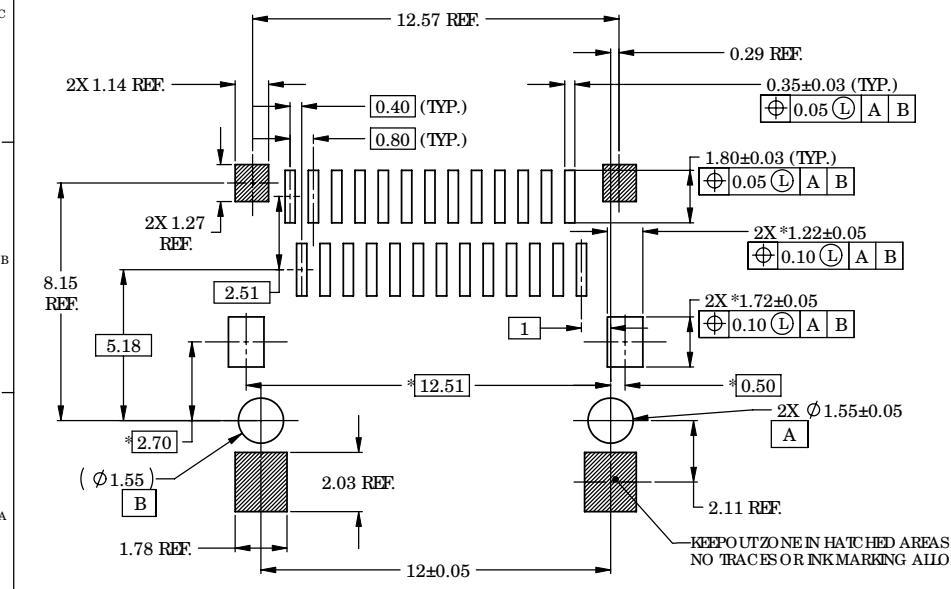


REVISIONS				
REV.	BY	DESCRIPTION	DATE	APPROVED
K		TOLERANCE ADDED TO 13.78	APR 16 06	RLJ



PART NUMBER	PACKAGING	CONTACT PLATING
FS1-R26-2001	TAPE AND REEL	30µ" GOLD OVER 50µ" NICKEL IN CONTACT AREAS 100µ" MATTE TIN OVER 50µ" NICKEL IN SOLDER AREAS
FS1-R26-3001		15µ" GOLD OVER 50µ" NICKEL IN CONTACT AREAS 100µ" MATTE TIN OVER 50µ" NICKEL IN SOLDER AREAS



NOTES

- 1) MATERIAL
HOUSING: SOLDER REFLOW PROCESS COMPATIBLE LCP, UL94V-0
CONTACTS: PHOSPHOR BRONZE
- 2) ROHS COMPLIANT
- 3) SOLDER TAB PLATING:
50 - 75 MICRONS OF NICKEL UNDER PLATE ALL OVER
100 - 150 MICRONS OF NO WHISKER MATTE TIN.
- 4) PERFORMANCE
ELECTRICAL: 0.5 AMPS MAX PER CONTACT
MECHANICAL: 250 MATING CYCLES MINIMUM
- 5) COMPLES WITH SFF-8086 EXCEPT WHERE NOTED "86"

THIS DOCUMENT CONTAINS PROPRIETARY INFORMATION AND SUCH INFORMATION MAY NOT BE DISCLOSED TO OTHERS FOR ANY PURPOSE OR USED FOR MANUFACTURING PURPOSES WITHOUT PERMISSION FROM AMPHENOL CANADA CORP.

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE:		APPROVALS		DATE	Amphenol Canada Corp.	
DRAWN	YK	28/SEP/06	DATE	DATE		
DESIGNER	YK	28/SEP/06	DATE	DATE	SFF 26 POSITION RECEPT, WITH SOLDER TABS	
CHECKED	YK	28/SEP/06	DATE	DATE		
QA APPR					P-FSI-R26-X001	
ENG. DES. NO.	EAR	REV. NO.	C	REV. NO.		NIS
COLLIDION NO.	03554	REV. APPR			REV. NO.	SFF
					REV. NO.	1 OF 1

RECOMMENDED PCB LAYOUT

DO NOT SCALE DRAWING